

# DS30BA101

## 3.125 Gbps Differential Buffer

### General Description

The DS30BA101 is a high-speed differential buffer for cable driving, signal buffering, and signal repeating applications. Its fully differential signal path ensures exceptional signal integrity and noise immunity. The DS30BA101 drives both differential and single-ended transmission lines at data rates up to 3.125 Gbps.

The output voltage amplitude is adjustable via a single external resistor for cable driving applications into  $75\Omega$  single-ended and  $100\Omega$  differential mode impedances.

The DS30BA101 is powered from a single 3.3V supply and consumes 165 mW (typical). It operates over the full industrial temperature range of  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$  and is available in a 4 x 4 mm 16-pin LLP package.

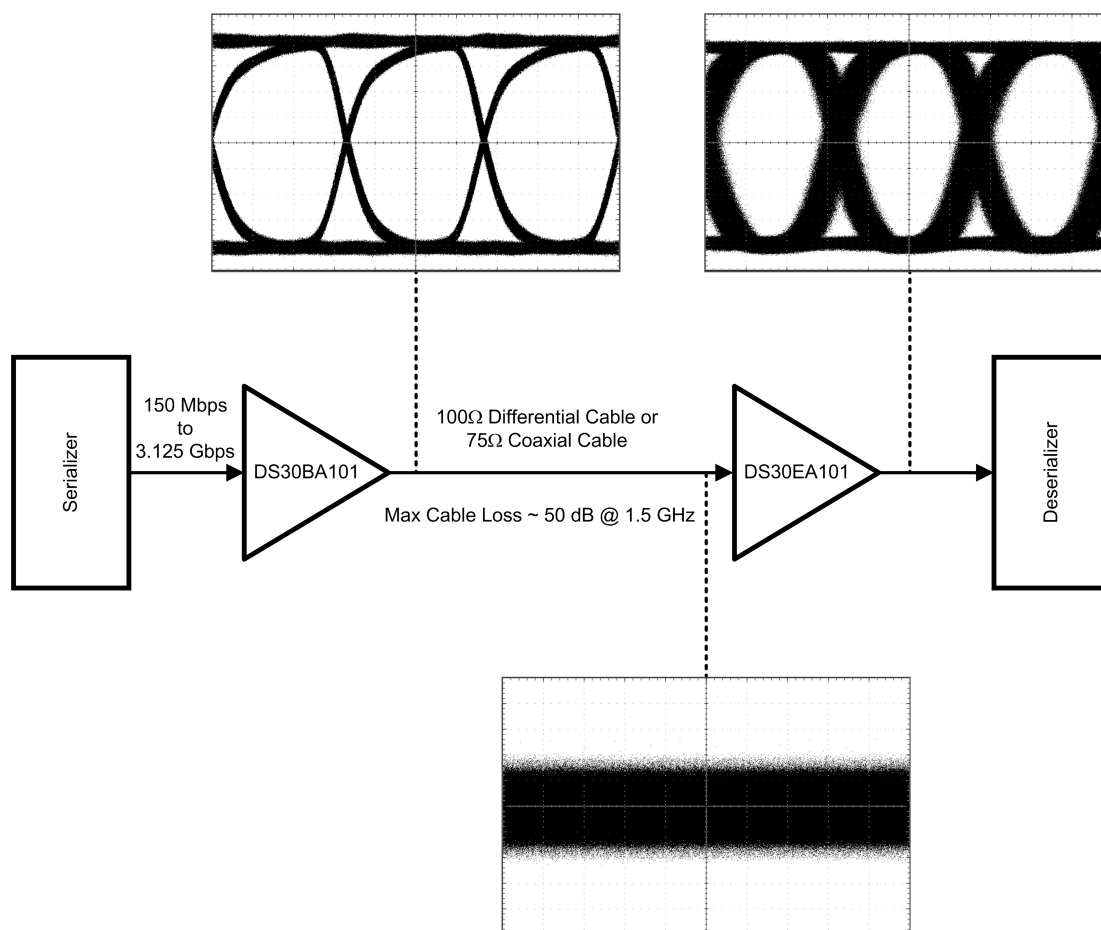
### Features

- Data rates from DC to 3.125 Gbps
- Supports SD and HD video resolutions
- Power consumption: 165 mW typical
- Industrial temperature range:  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$

### Applications

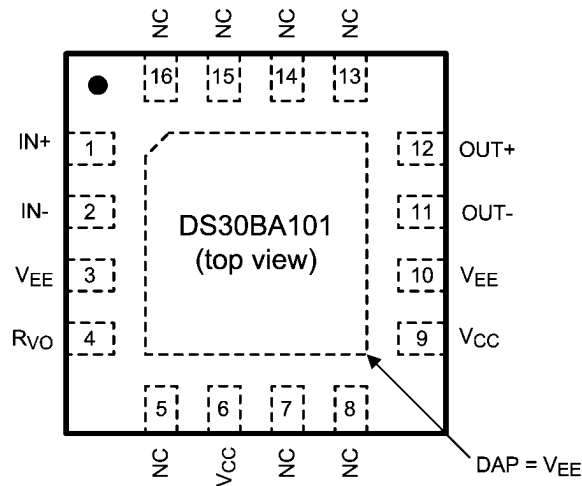
- Cable extension
- Signal buffering and repeating
- Security and surveillance

### Typical Application



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Connection Diagram



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The exposed die attach pad is a negative electrical terminal for this device. It should be connected to the negative power supply voltage.

16-Pin LLP  
Order Number DS30BA101SQ  
Package Number SQB16A

Ordering Information

Part Number	Package	Quantity
DS30BA101SQ	16-Pin LLP, 4.0 x 4.0 x 0.8 mm, 0.65 mm pitch	Reel of 1000
DS30BA101SQE	16-Pin LLP, 4.0 x 4.0 x 0.8 mm, 0.65 mm pitch	Reel of 250
DS30BA101SQX	16-Pin LLP, 4.0 x 4.0 x 0.8 mm, 0.65 mm pitch	Reel of 4500

## Pin Descriptions

Pin	Name	I/O, Type	Description
1	IN+	I, CML	Non-inverting input.
2	IN-	I, CML	Inverting input.
3	V <sub>EE</sub>	Ground	Negative power supply (ground).
4	R <sub>VO</sub>	I, Analog	Output voltage level control. Connect a resistor between this pin and V <sub>CC</sub> to set the output voltage.
5	NC	N/A	No connect. Not bonded internally.
6	V <sub>CC</sub>	Power	Positive power supply (+3.3V).
7	NC	N/A	No connect. Not bonded internally.
8	NC	N/A	No connect. Not bonded internally.
9	V <sub>CC</sub>	Power	Positive power supply (+3.3V).
10	V <sub>EE</sub>	Ground	Negative power supply (ground).
11	OUT-	O, Data	Inverting output.
12	OUT+	O, Data	Non-inverting output.
13	NC	N/A	No connect. Not bonded internally.
14	NC	N/A	No connect. Not bonded internally.
15	NC	N/A	No connect. Not bonded internally.
16	NC	N/A	No connect. Not bonded internally.
DAP	V <sub>EE</sub>	Ground	Connect exposed DAP to negative power supply (ground).

## Absolute Maximum Ratings *(Note 1)*

Supply Voltage:	3.6V
Input Voltage (all inputs)	-0.3V to $V_{CC}+0.3V$
Output Current	28 mA
Storage Temperature Range	-65°C to +150°C
Junction Temperature	+125°C
Package Thermal Resistance	
$\theta_{JA}$ 16-pin LLP	+58°C/W
$\theta_{JC}$ 16-pin LLP	+21°C/W

ESD Rating (HBM)	$\geq \pm 4.5$ kV
ESD Rating (MM)	$\geq \pm 250$ V
ESD Rating (CDM)	$\geq \pm 2$ kV

## Recommended Operating Conditions

Supply Voltage ( $V_{CC}$ ):	3.3V $\pm 5\%$
Operating Free Air Temperature ( $T_A$ )	-40°C to +85°C

## DC Electrical Characteristics

Over recommended supply voltage and operating temperature ranges, unless otherwise specified. *(Note 2, Note 3)*

Symbol	Parameter	Conditions	Reference	Min	Typ	Max	Units
$V_{ICM}$	Input Common Mode Voltage		IN+, IN-	1.1 + $V_{ID}/2$		$V_{CC} - V_{ID}/2$	V
$V_{ID}$	Input Voltage Swing	Differential		100		2200	mV <sub>P-P</sub>
$V_{OCM}$	Output Common Mode Voltage		OUT+, OUT-		$V_{CC} - V_{OUT}$		V
$V_{OUT}$	Output Voltage	Single-ended, 75 $\Omega$ load, $R_{VO} = 750\Omega$			800		mV <sub>P-P</sub>
		Single-ended, 50 $\Omega$ load, $R_{VO} = 953\Omega$			400		mV <sub>P-P</sub>
$I_{CC}$	Supply Current				50	59	mA

## AC Electrical Characteristics

Over recommended supply voltage and operating temperature ranges, unless otherwise specified. *(Note 2, Note 3)*

Symbol	Parameter	Conditions	Reference	Min	Typ	Max	Units
$DR_{IN}$	Input Data Rate		IN+, IN-			3125	Mbps
$t_{TLH}$	Transition Time Low to High	20% - 80% <i>(Note 4)</i>	OU++, OUT-		90	130	ps
$t_{THL}$	Transition Time High to Low				90	130	ps

**Note 1:** "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions indicate conditions at which the device is functional and the device should not be operated beyond such conditions.

**Note 2:** The Electrical Characteristics tables list guaranteed specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not guaranteed.

**Note 3:** Typical values represent most likely parametric norms at  $V_{CC} = +3.3V$ ,  $T_A = +25^\circ C$ , and at the Recommended Operating Conditions at the time of product characterization and are not guaranteed.

**Note 4:** Specification is guaranteed by characterization and is not tested in production.

## Device Operation

### INPUT INTERFACING

The DS30BA101 accepts either differential or single-ended input. DC-coupled inputs must be kept within the specified common-mode range.

### OUTPUT INTERFACING

The DS30BA101 uses current mode outputs. Single-ended output levels are 800 mV<sub>P-P</sub> into 75Ω AC-coupled coaxial cable with an R<sub>VO</sub> resistor of 750Ω, or 400 mV<sub>P-P</sub> (800 mV<sub>P-P</sub> differential) into 100Ω differential cable with an R<sub>VO</sub> resistor of 953Ω. The output voltage level is controlled by the value of the R<sub>VO</sub> resistor connected between the R<sub>VO</sub> pin and V<sub>CC</sub>.

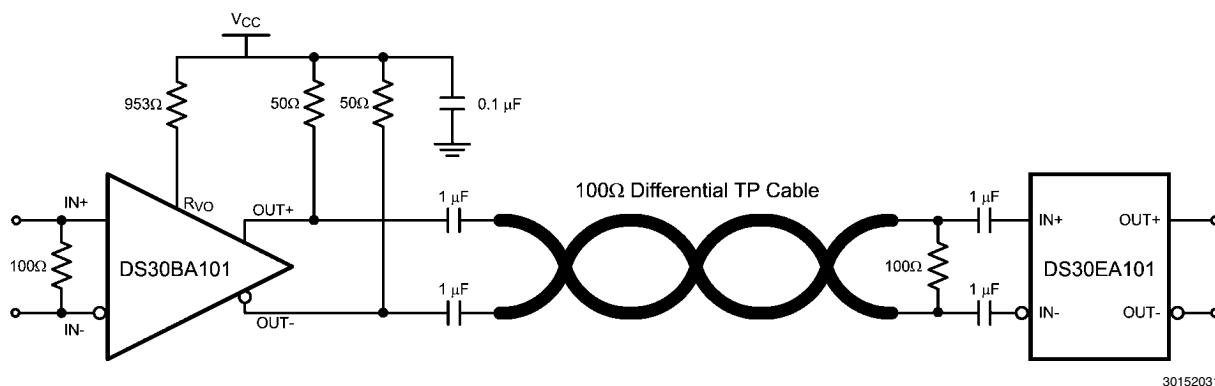
The R<sub>VO</sub> resistor should be placed as close as possible to the R<sub>VO</sub> pin. In addition, the copper in the plane layers below the R<sub>VO</sub> network should be removed to minimize parasitic capacitance.

Figure 1 and Figure 2 show the typical configurations for differential output and single-ended output, respectively. For single-ended output, the unused output must be properly terminated as shown.

## Application Information

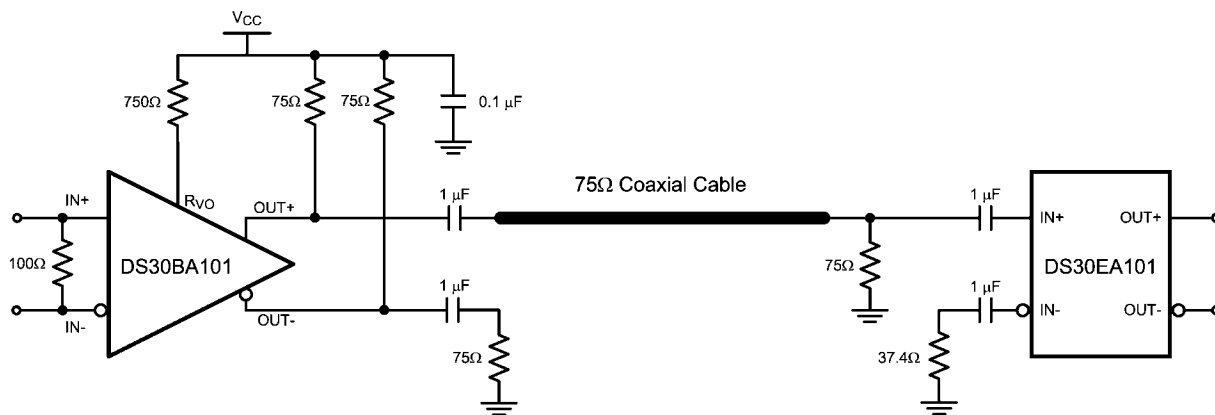
### CABLE EXTENDER APPLICATION

The DS30BA101 together with the DS30EA101 form a cable extender chipset optimized for extending serial data streams from serializer/deserializer (SerDes) pairs and FPGAs over 100Ω differential cables and 75Ω coaxial cables. Setting the correct DS30BA101 output amplitude and proper cable termination are essential for optimal operation. Figure 1 shows the recommended chipset configuration for 100Ω differential cable and Figure 2 shows the recommended chipset configuration for 75Ω coaxial cable.



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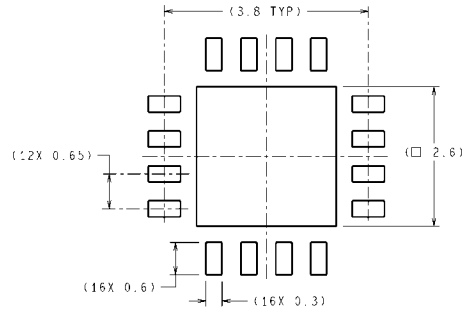
FIGURE 1. Cable Extender Chipset Application Circuit for 100Ω Differential Cable



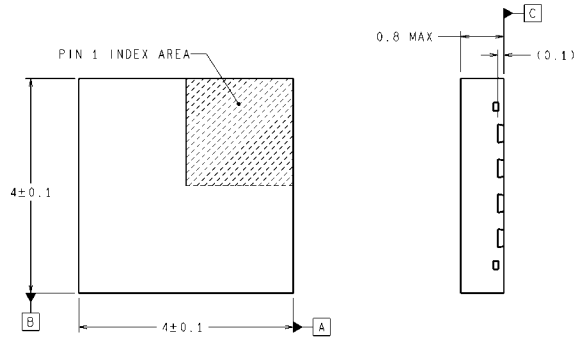
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FIGURE 2. Cable Extender Chipset Application Circuit for 75Ω Coaxial Cable

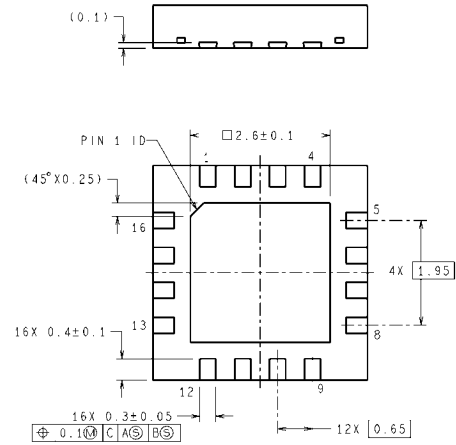
# Physical Dimensions inches (millimeters) unless otherwise noted



RECOMMENDED LAND PATTERN



DIMENSIONS ARE IN MILLIMETERS  
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**16-Pin LLP**  
**Order Number DS30BA101SQ**  
**Package Number SQB16A**

SQB16A (Rev A)

## Notes

## Notes



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### Applications

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